



# Mechanics Design



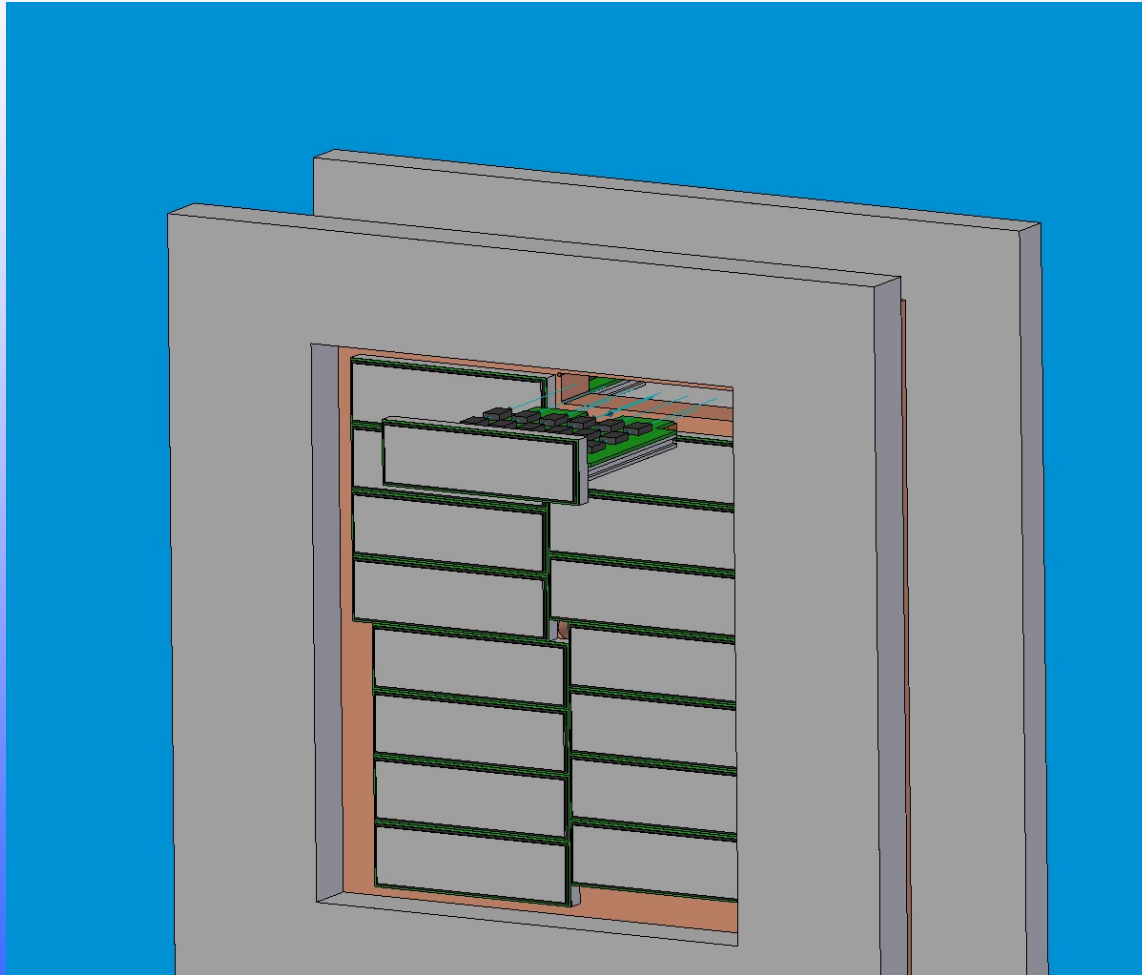
## Requirements:

- The mechanics should meet the following requirements:
- Mechanical stability and high precision positioning of the modules.
- Cooling of the chips to  $-15^{\circ}\text{C}$ .
- Easy maintenance access and module replacement.
- Operate under ambient pressure or vacuum.
- Support for the front end electronics.

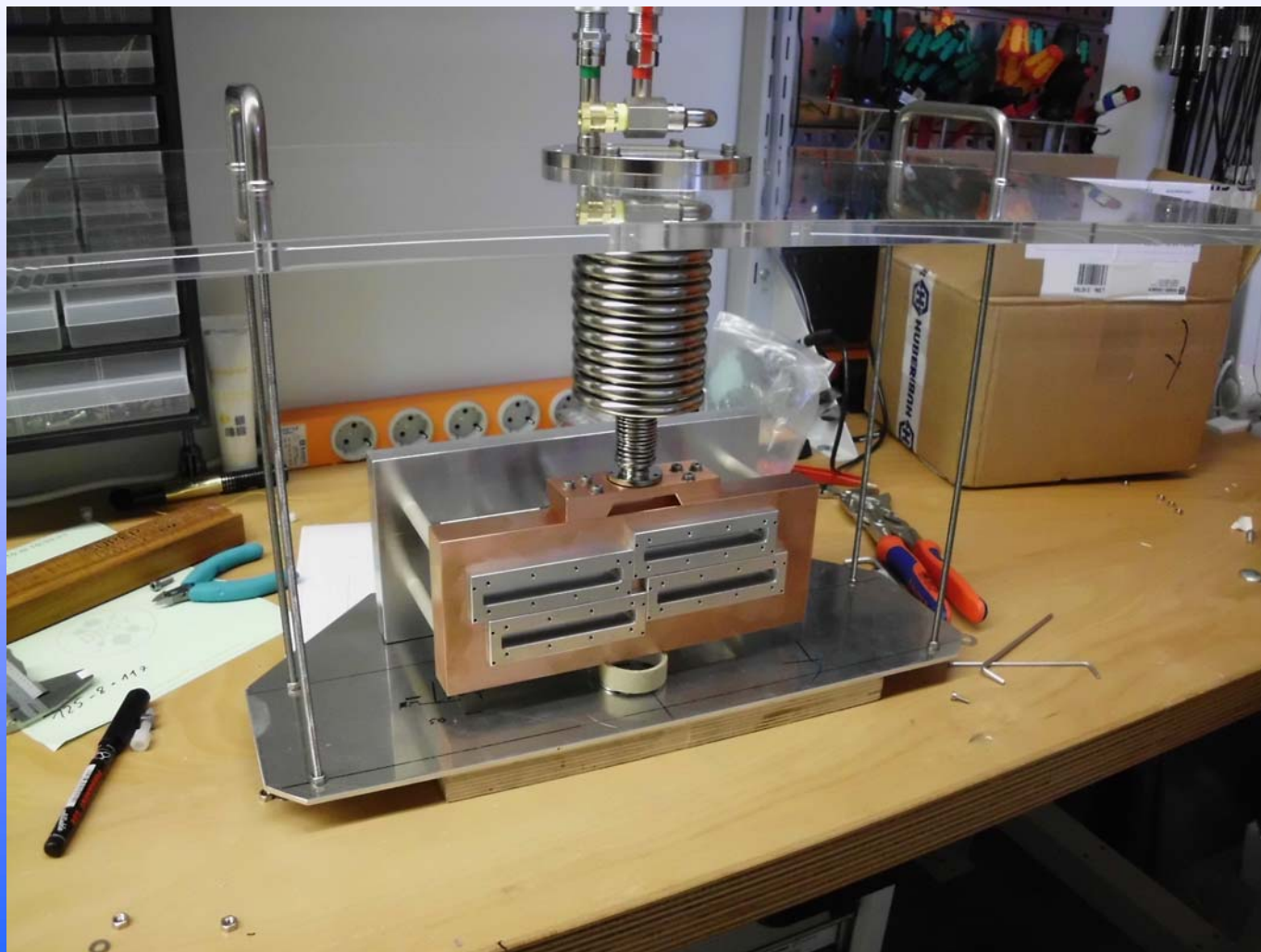


1k x 1k Sensor

Front View



# AGIPD-Dummy in Lab





## **CO<sub>2</sub> - Cooling:**

### **CO<sub>2</sub> Cooler for XFEL Detector R&D**

For XFEL detector R&D activities DESY is interested in acquiring a CO<sub>2</sub> cooler based on the Nikhef 2-PACL technique.

### **Global Specifications**

Nikhef designs and builds a cooling plant for DESY with the following specifications:

1. Cooling Power maximum 1.2 kW
2. Minimum evaporating temperature required -15°C
3. Temperature stability in time of < 2°C
4. Maximum cooling volume of detector: < 1 liter
5. Ambient temperature < 35°C
5. No parallel cooling loops.
6. Distance of cooling machine to experiment < 5 meter



## AGIPD Bare Module

### Chip Parameters:

No. of Pixels 64 x 64  
Total Area 12.94 x 13.74

(assuming 800um periphery + 70um die seal ring)

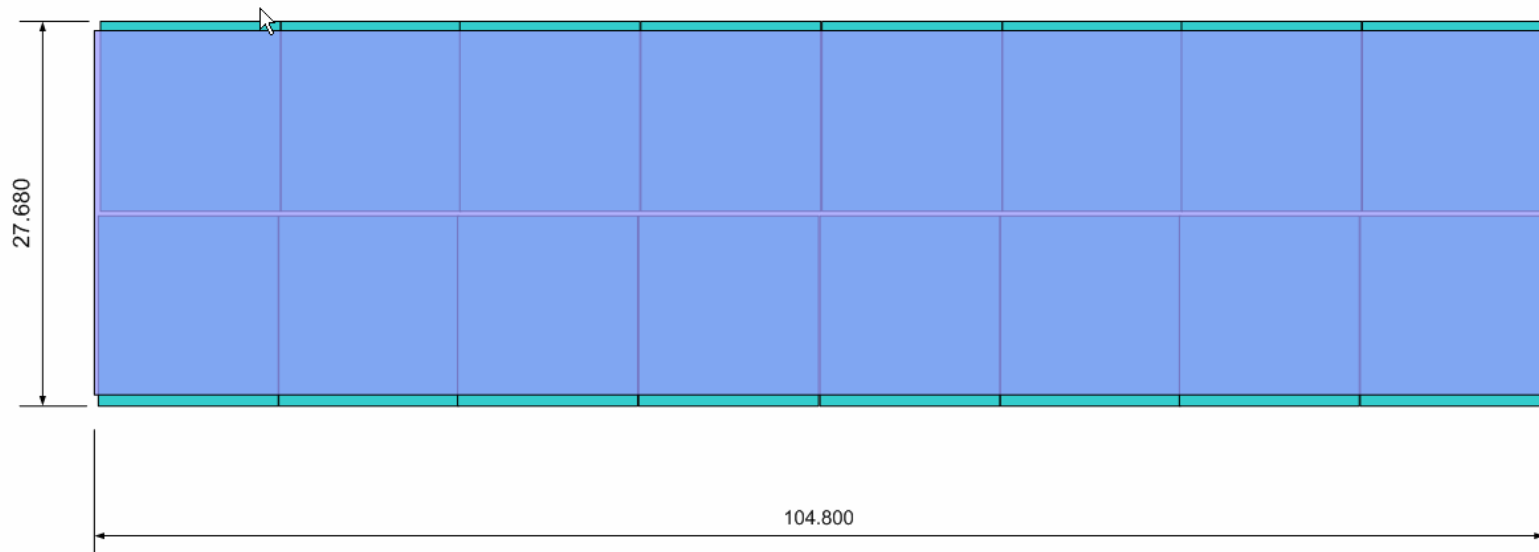
### Module Parameters:

No. of Pixels 519 x 129  
Active Area 103.800 x 25.800  
Total Area (Sensor) 104.800 x 26.800  
Baseplate 104.800 x 27.680  
HDI 104.870 x 28.680  
Support 104.940 x 28.780

(assuming 500um Sensor Guard Ring)

### Multi Module Parameters:

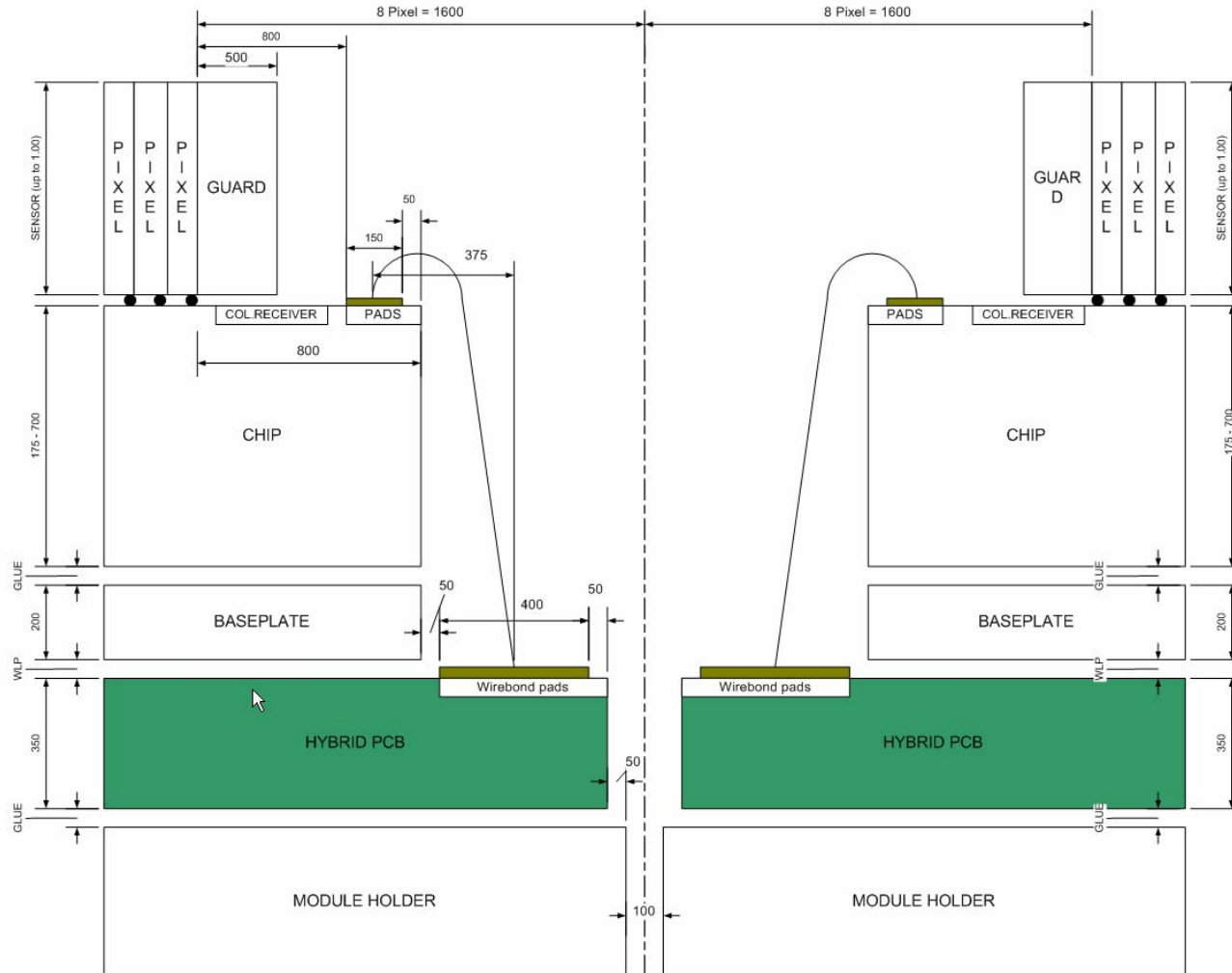
No. of dead Gap Pixels (2x3) x (2x8)  
No. of Pixels incl. Gap 525 x 145  
Module Step 105.000 x 29.00





# Dimensions

## Module 2 Module Longside





# Dimensions

## Module 2 Module Shortside

